



# 10/B  
10-18-02  
500.39590X00 *Molteni*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MIYAKI et al.  
Serial No.: 09/785,452  
Filed: February 20, 2001  
For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE  
AND METHOD OF MANUFACTURING THE SAME  
Group: 2827  
Examiner: L. Cruz

AMENDMENT

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

October 7, 2002

Sir:

In response to the Office Action dated June 6, 2002, the period of response for which extension is requested by the attached Petition for Extension of Time, please amend the above-identified application as follows:

In the Claims:

✓  
Please cancel claims 1, 8 and 11-15 without prejudice.

Please amend claims 2-7, 9 and 10 as follows:

2. (Amended) A semiconductor integrated circuit device comprising:

B1  
a conductive connecting member;  
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a connected member in which a metal layer including a palladium layer is

provided at a first portion to which said connecting member is connected, and an

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See Col. 40  
(See that all layers are "connected")  
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